LEOCO CORPORATION PRODUCTION SPECIFICATION No. S-96-5016 REV 2

* 5000 Series and 5016 Series Connector *

This product specification contains the test method, the general performance and requirements for interconntection system connector with 5000 series socket ,5016 series header and 3979/3983 series crimp terminal.

1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构和尺寸依据所提供的产品图面.

2. Characteristics 特性:

Current rating 额定电流: 7A AC,DC Voltage rating 额定电压: 250V AC,DC Temperature rating 额定温度: -25 $^{\circ}$ $^{\circ}$ ~ +105 $^{\circ}$ $^{\circ}$

Applicable wire 适用线材: conductor construction size #18 ~ #24

3. Electrical performance 电气特性:

ITEM	DESCRIPTION	TEST METHOD & CONDITION	REQUIREMENT					
	内容	测试方法与条件	需 求					
3-1	Contact Resistance	It should be tested in accordance with	Initial: 20 m Ω max.					
	接触阻抗	method EIA-364-23	After environmental					
			Test: 40 m Ω max.					
3-2	Insulation	It should be tested in accordance with	Initial: $1000M\Omega$ min.					
	Resistance	Method EIA-364-21	After humidity test					
	绝缘阻抗		500 M Ω min.					
3-3	Dielectric	Unmated connectors shall be tested in	No evidence of break-					
	Withstanding	Accordance with method EIA-364-20	Down and flashover					
	Voltage	When the AC 1500 V rms for one minute						
	耐电压	applied between adjacent contacts.						
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	耐电压	applied between adjacent contacts.							
4. Mechanical Performance 机械特性:									
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需 求						
4-1	Crimp Tensile Strength 铆合张力强度	Pulling load shall be applied between Correctly crimped contact and wire at a constant speed. Pulling speed: 25 mm / minute.	AWG #18: 10.0 kgf min. AWG #20: 6.0 kgf min. AWG #22:4.0 kgf min. AWG #24: 2.5 kgf min.						
4-2	Contact Insertion Force 接触插入力	The force required to insert a contact into a housing. Inserting speed: 25 mm / minute.	1.25kgf max.						
4-3	Contact removal Force 接触拨出力	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm / minute.	2.0 Kgf min.						
4-4	Post retention force 保持力	The end of a post shall be pushed in a perpendicular to base housing at a constant speed of 25mm/minute	_						
4-5	Insertion Force 插入力	Housing with contact mating header at a constant speed of 25 mm / minute.	2.0 kgf max						
4-6	Withdrawal Force 拨出力	Housing with contact mating header, Pull out from header at speed 25 mm / minute.	0.5 kgf min						
4-7	Durability 耐久力	It should be tested in accordance with method EIA-364-09 Connector shall be subjected to 100 cycles of insertion and withdrawal	No defects. Contact resistance shall be $20m\Omega$ max						

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ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件		REQUIREMENT 需 求		
4-8	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	The connector mated PCB shall be vibrated in accordance with method EIA-364-28. There shall be no current discontinuity longer than 1 microsecond during the test Frequency: 10-55-10 Hz / min. Amplitude: 1.52mm Period: 2 hours for each direction		No evidence of loosening of parts or electric discontinuity. Contact resistance less than twice of initial.		
5. Envir	onmental Performanc	e 环境特性:				
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件		REQUIREMENT 需 求		
5-1	Humidity 耐湿性	The unmated connector shall be tested accordance with method EIA-364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.	lı C	NO damage. Contact resistance less Than twice of initial. Insulation resistance: to paragraph 3-2. Dielectric withstand ing voltage: to paragraph 3-3		
5-2	Salt Spray 盐雾试验	Connector shall be tested in accordance with method EIA-364-26 Temperature: 35±2 °C Density: 5 % in weight. Period: 24 hours.		NO damage. Contact resistance less than twice of initial.		
5-3	Solder ability 着锡性	Connector termination ends shall be checked for solder ability in accordance with method EIA-364-252 Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.)	NO damage. Minimum: 95 % immersed area		
5-4	Resistance to Soldering Heat 附着耐热性	Specimen shall be mounted on PCB. Solder temperature: 260±5 °C Immersion period: 5±0.5 sec.		NO damage ar deformation.	nd	
APPR E	3Y: TONY 02/11'14	CHKD BY: CHARD 02/11'14	SPEC	SPEC BY: Angel		

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